

Title (en)

COMPOSITE COPPER PARTICLES AND PRODUCTION METHOD THEREFOR

Title (de)

VERBUNDKUPFERPARTIKEL UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)

PARTICULES DE CUIVRE COMPOSITES ET PROCÉDÉ DE PRODUCTION DE CELLES-CI

Publication

EP 3031551 A1 20160615 (EN)

Application

EP 14834408 A 20140801

Priority

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Abstract (en)

The composite copper particle of the invention is a composite copper particle including a flake-like copper particle and a plurality of inorganic oxide particles which are finer than the flake-like copper particle. The inorganic oxide particles are unevenly distributed on a surface of the flake-like copper particle. The composite copper particle preferably has a volume cumulative particle diameter D 50 at a cumulative volume of 50 vol% as measured by a laser diffraction scattering method of 0.1 µm to 10 µm. An aspect ratio of the maximum diameter d of a plane of the composite copper particle to the maximum thickness t of the composite copper particle, d/t, is preferably 5 to 30. The inorganic oxide particles preferably have a higher hardness than copper.

IPC 8 full level

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